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HD74SSTV16859

1:2 13-bit SSTL_2 Registered Buffer

REJ03D0832-0900

(Previous: ADE-205-337H)

Rev.9.00 Apr 07, 2006

Description

The HD74SSTV16859 is a 1:2 13-bit registered buffer designed for 2.3 V to 2.7 V Vcc operation and LVCMOS reset (RESET) input / SSTL_2 data (D) inputs and CLK input.

Data flow from D to QA, QB is controlled by differential clock pins (\overline{CLK} , \overline{CLK}) and the \overline{RESET} . Data is triggered on the positive edge of the positive clock (\overline{CLK}), and the negative clock (\overline{CLK}) must be used to maintain noise margins. When \overline{RESET} is low, all registers are reset and all outputs are low.

To ensure defined outputs from the register before a stable clock has been supplied, RESET must be held in the low state during power up.

Features

- Supports LVCMOS reset (RESET) input / SSTL_2 data (D) inputs and CLK input
- Differential SSTL_2 (Stub series terminated logic) CLK signal
- Flow through architecture optimizes PCB layout
- Ordering Information

Part Name	Package Type	Package Code (Previous code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74SSTV16859TEL	TSSOP-64 pin	PTSP0064KA-A	T	EL (1,000 pcs / Reel)
		(TTP-64DV)		

Function Table

	Out	puts			
RESET	CLK	CLK	D	QA	QB
L	X	X	X	L	L
Н	+	\uparrow	Н	Н	Н
Н	+	\uparrow	L	L	L
Н	L or H	H or L	Х	Q_0 *1	Q_0^{*1}

H: High level

L: Low level

X: Immaterial

↑: Low to high transition

 \downarrow : High to low transition

Note: 1. Output level before the indicated steady state input conditions were established.

Pin Arrangement

Q12A 1	64	V_{DDQ}
Q11A 2	63	GND
Q10A 3	62	D12
Q09A 4	61	D11
Q08A 5	60	Vcc
V _{DDQ} 6		V_{DDQ}
GND 7		GND
Q07A 8	57	D10
Q06A g	56	D9
Q05A 10	55	D8
Q04A 11	54	GND
Q03A 12	53	D7
Q02A 13	52	D6
Q01A 14	51	RESET
GND 15	50	GND
Q00A 16	49	CLK
Q12B 17	48	CLK
V _{DDQ} 18	47	V _{DDQ}
Q11B 19	46	Vcc
Q10B 2	45	V _{REF}
Q09B 2	1 44	D5
Q08B 2:	2 43	GND
Q07B 2:	3 42	D4
Q06B 2	41	D3
Q05B 2	40	D2
GND 2	39	GND
V _{DDQ} 2		V_{DDQ}
Q04B 2		V _{CC}
Q03B 2	36	D1
Q02B 3	35	D0
Q01B 3	1 34	GND
Q00B 3:	2 33	V_{DDQ}
	(Top view)	
	(10p view)	

Absolute Maximum Ratings

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V _{CC} or V _{DDQ}	-0.5 to 3.6	V	
Input voltage *1	Vı	-0.5 to V _{DDQ} +0.5	V	
Output voltage *1	Vo	-0.5 to V _{DDQ} +0.5	V	
Input clamp current	I _{IK}	±50	mA	$V_I < 0$ or $V_I > V_{CC}$
Output clamp current	I _{OK}	±50	mA	$V_O < 0$ or $V_O > V_{DDQ}$
Continuous output current	Io	±50	mA	$V_O = 0$ to V_{DDQ}
V _{CC} , V _{DDQ} or GND current / pin	I _{CC} , I _{DDQ} or I _{GND}	±100	mA	
Maximum power dissipation	P _T	1	W	TSSOP
at Ta = 55°C (in still air)				
Storage temperature	Tstg	-65 to +150	°C	

Notes: Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device.

These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

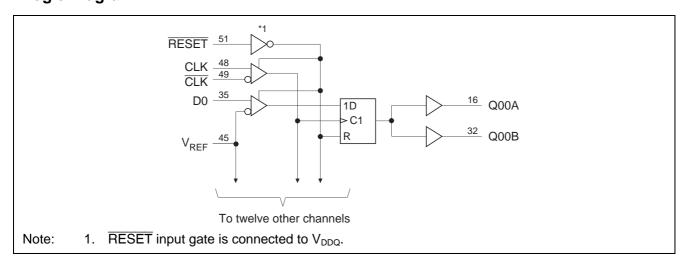
 The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

Recommended Operating Conditions

	Item	Symbol	Min	Тур	Max	Unit	Conditions
Supply voltage		V _{CC}	V_{DDQ}	2.5	2.7	V	
Output supply	/ voltage	V_{DDQ}	2.3	2.5	2.7	V	
Reference vo	ltage	V_{REF}	1.15	1.25	1.35	V	$V_{REF} = 0.5 \times V_{DDQ}$
Termination v	oltage	V_{TT}	V _{REF} -40 mV	V_{REF}	V _{REF} +40 mV	V	
Input voltage		VI	0	3-1	V _{cc}	V	
AC high level	input voltage	V _{IH}	V _{REF} +310 mV	4	<u> </u>	V	D
AC low level	input voltage	V _{IL}	0- 1		V _{REF} -310 mV	V	D
DC high level	input voltage	VIH	V _{REF} +150 mV	_	_	V	D
DC low level	input voltage	V _{IL}		_	V _{REF} -150 mV	V	D
High level inp	ut voltage	V _{IH}	1.7	_	V _{DDQ} +0.3	V	RESET
Low level inp	ut voltage	V _{IL}	-0.3	_	0.7	V	RESET
Differential	(Common mode range)	V _{CMR}	0.97	_	1.53	V	CLK, CLK
input voltage	(Minimum peak to	V_{PP}	360	_	_	mV	CLK, CLK
	peak input)						
High level out	tput current	ОН	_		-20	mA	
Low level out	put current	l _{OL}			20	mA	
Operating ten	nperature	Ta	0	_	70	°C	

Note: The $\overline{\text{RESET}}$ input of the device must be held at V_{DDQ} or GND to ensure proper device operation. The differential inputs must not be floating, unless $\overline{\text{RESET}}$ is low.

Logic Diagram



Electrical Characteristics

Item		Symbol	V _{CC} (V)	Min	Тур	Max	Unit	Test Conditions
Input diode voltage)	V_{IK}	2.3			-1.2	V	$I_{IN} = -18 \text{ mA}$
Output voltage		V _{OH}	2.3 to 2.7	V _{CC} -0.2		(A)	V	I _{OH} = -100 μA
			2.3	1.95		V _{DDQ}	0 1	$I_{OH} = -16 \text{ mA}$
		V _{OL}	2.3 to 2.7		-	0.2		I _{OL} = 100 μA
			2.3	0	1	0.35		I _{OL} = 16 mA
Input current (A	III inputs)	I _{IN}	2.7		-	±5	μA	$V_{IN} = 2.7 \text{ V or } 0$
Quiescent supply of	current	Icc *2	2.7		-	45	mA	$V_{IN} = V_{IH(AC)}$ or $V_{IL(AC)}$, $I_O = 0$
Standby current		I _{CC (stdy)}	2.7		-9,	10	μΑ	RESET = GND
Dynamic operating	clock only	I _{CCD} *2	2.7	- <		90	μΑ/	$\overline{RESET} = V_{CC},$
			15				clock	$V_I = V_{IH(AC)}$ or $V_{IL(AC)}$,
							MHz	CLK and CLK switching 50%
								duty cycle
Dynamic operating per each		I _{CCD} *2	2.7		_	20	μΑ/	$\overline{RESET} = V_{CC},$
data input							clock	$V_I = V_{IH(AC)}$ or $V_{IL(AC)}$,
			A Y				MHz/	CLK and CLK switching 50%
							data	duty cycle. One data input
		66					input	switching at half clock
								frequency, 50% duty cycle.
Output high *3		r _{OH}	2.3 to 2.7	7	_	22 *4	Ω	$I_{OH} = -20 \text{ mA}$
Output low *3		r _{OL} ▼	2.3 to 2.7	7	_	22 *4	Ω	$I_{OL} = 20 \text{ mA}$
r _{OH} - r _{OL} each		$r_{O(\Delta)}$	2.5	_	_	4	Ω	I _O = 20 mA, Ta = 25°C
separate bit *3								
Input Da	ata inputs	C _{IN}	2.5 ^{*1}	2.5		3.5	pF	$V_I = V_{REF} \pm 310 \text{ mV}$
capacitance CI	LK and CLK			2.5	_	3.5		$V_{CMR} = 1.25 \text{ V}, V_{PP} = 360 \text{ mV}$
R	ESET			_	3.0	_		$V_I = V_{CC}$ or GND

Notes: 1. All typical values are at $V_{CC} = 2.5 \text{ V}$, $Ta = 25^{\circ}C$.

- 2. Total I_{CC} (max) = I_{CC} + { I_{CCD} (clock)×f(clock)} + { I_{CCD} (Data)×1/2f(clock)×13}
- 3. This is effective in the case that it did terminate by resistance.
- 4. See figure. 1, 2

Switching Characteristics

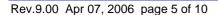
ltem		Symbol	$V_{CC} = 2.5 \pm 0.2 \text{ V}$		Unit	Test Condition	
			Min	Max	Offic	rest Condition	
Clock frequenc	y *1	f _{clock}	_	200	MHz		
Setup time	Fast slew rate *4, 6	t _{su}	0.75	_	ns	Data before CLK↑, CLK↓	
	Slow slew rate *5, 6		0.9	_			
Hold time	Fast slew rate *4, 6	t _h	0.75	_	ns	Data after CLK↑, CLK↓	
	Slow slew rate *5, 6		0.9	_			
Differential inputs active time		t _{act}	22	_	ns	Data inputs must be low after RESET high.	
Differential inputs inactive time		t _{inact}	22	_	ns	Data and clock inputs must be held at valid levels (not floating) after RESET low.	
Pulse width		t _w	2.5	_	ns	CLK, CLK "H" or "L"	
Output slew *3		t _{SL}	1	4	volt/ns		

 $(C_L = 30 \text{ pF}, R_L = 50 \Omega, V_{REF} = V_{TT} = V_{DDQ} \times 0.5)$

Item	Symbol	Vc	_C = 2.5 ± 0.2 V		Unit	FROM	то
item	Syllibol	Min	Тур	Max	Ollit	(Input)	(Output)
Maximum clock frequency	f _{max}	200	_	7	MHz		
Propagation delay time *2	t _{PLH} , t _{PHL}	1.1	_	2.8	ns	CLK, CLK	QA, QB
	t _{PHL}	_		5.0	6. ON	RESET	QA, QB

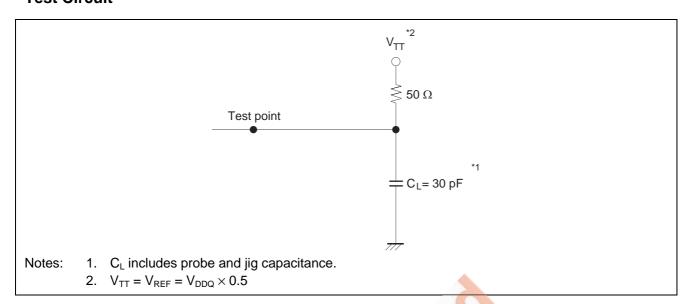
Notes: 1. Although the clock is differential, all timing is relative to CLK going high and CLK going low.

- 2. This timing relationship is specified into test load (see waveforms 3, 4) with all of the outputs switching.
- 3. Assumes into an equivalent, distributed load to the address net structure defined in the application information provided in this specification.
- 4. For data signal input slew rate ≥ 1 V/ns.
- 5. For data signal input slew rate ≥ 0.5 V/ns and < 1 V/ns.
- 6. CLK, CLK signals input slew rates are ≥ 1 V/ns.

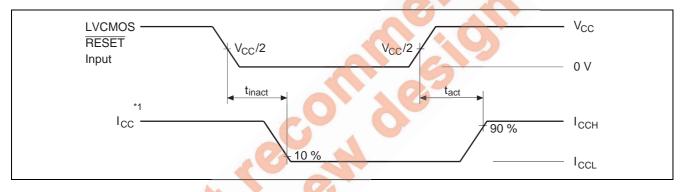




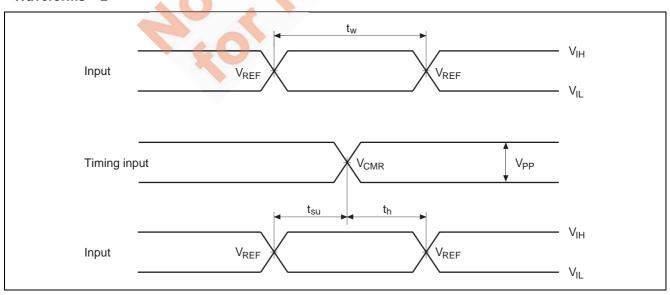
Test Circuit



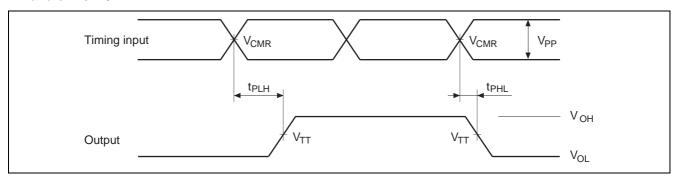
Waveforms - 1



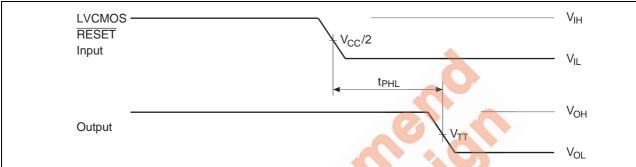
Waveforms - 2



Waveforms - 3



Waveforms - 4



Notes:

- 1. I_{CC} tested with clock and data inputs held at V_{CC} or GND, and $I_0 = 0$ mA.
- 2. All input pulses are supplied by generators having the following characteristics : PRR \leq 10 MHz, Zo = 50 Ω , input slew rate = 1 V/ns \pm 20% (unless otherwise specified).
- 3. The outputs are measured one at a time with one transition per measurement.
- 4. $V_{TT} = V_{REF} = V_{DDQ}/2$
- 5. V_{IH} = V_{REF}+310 mV (AC voltage levels) for differential inputs. V_{IH} = V_{CC} for LVCMOS input.
 6. V_{IL} = V_{REF}-310 mV (AC voltage levels) for differential inputs. V_{IL} = GND for LVCMOS input.
- 7. t_{PLH} and t_{PHL} are the same as t_{pd}

Application Data

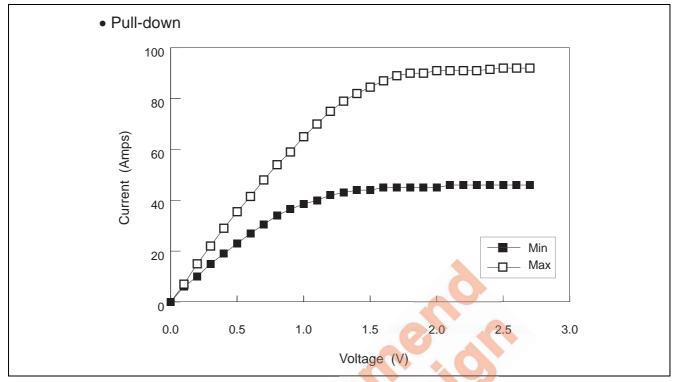


Figure 1

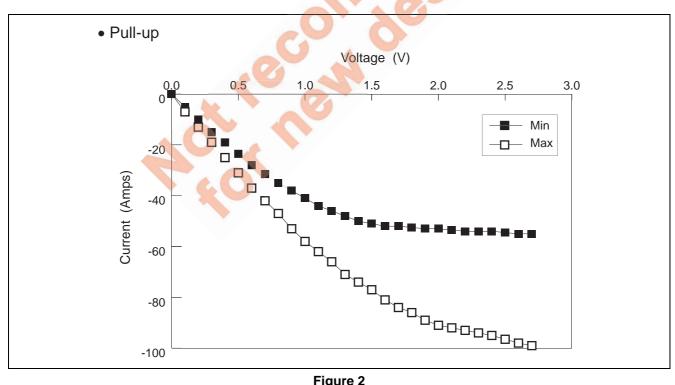
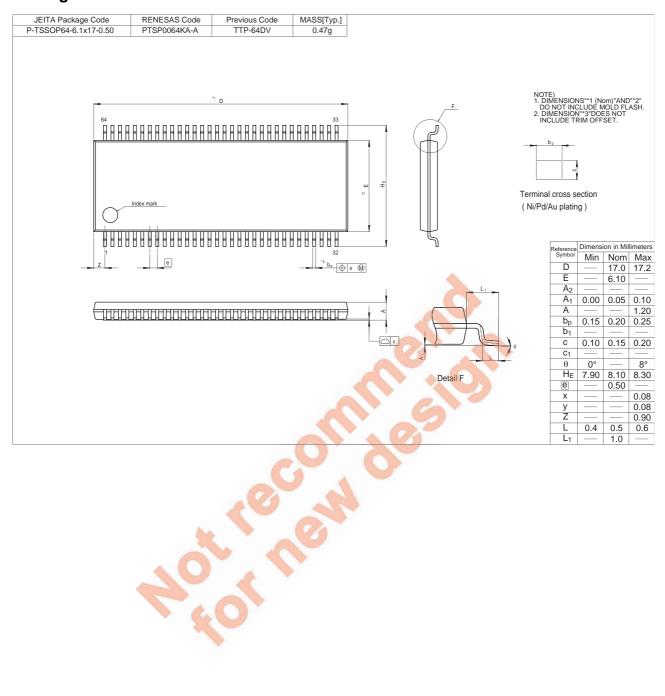


Figure 2

Curve Data

	Pull-	down	Pull-up		
Voltage (V)	I (mA)	I (mA)	I (mA)	I (mA)	
	Min	Max	Min	Max	
0.0	0	0	0	0	
0.1	6	7	-5	-7	
0.2	10	15	-10	-13	
0.3	15	22	-15	-19	
0.4	19	29	-19	-25	
0.5	23	35.5	-23.5	-31	
0.6	27	41.5	-28	-37	
0.7	30.5	48	-31.5	-42	
0.8	34	54	-35	-47	
0.9	36.5	59	-38	-53	
1.0	38.5	65	-41	-58	
1.1	40	70	_44	-62	
1.2	42	75	-46	-66	
1.3	43	79	-48	–71	
1.4	44	82	-50	-74	
1.5	44	84.5	-51	–77	
1.6	45	87	-52	-81	
1.7	45	89	-52	-84	
1.8	45	90	-52.5	-86	
1.9	45	90	-53	-89	
2.0	45	91	-53	– 91	
2.1	46	91	-53.5	-92	
2.2	46	91	-54	-93	
2.3	46	91	-54	-94	
2.4	46	91.5	-54	-95	
2.5	46	92	-54.5	-96.5	
2.6	46	92	- 55	-98	
2.7	46	92	-55	-99	

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